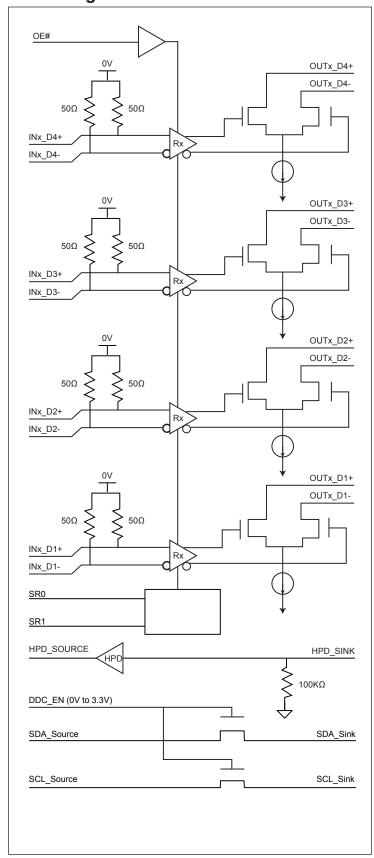


Block Diagram





Pin	Name	I/O Type	Descriptions			
1, 5, 12, 18, 24, 27, 31, 36, 37, 43	GND	POWER	GROUND			
2, 11, 15, 21, 26, 33, 40, 46	V_{DD}	POWER	POWER, 3.3V ±10%			
3	SR0	I	Slew Rate Control. Acceptable connections to SR0 pin are: resistor to 3.3V or short to GND. (internal 200K Ω pull-LOW)			
4	SR1	I	Slew Rate Control. Acceptable connections to SR1 pin are: resistor to 3.3V or short to GND. (internal 200K Ω pull-LOW)			
6, 10, 34, 35	NC	О	No Connect			
7	HPD_SOURCE	О	HPD_SOURCE: 0V to 3.3V (nominal) output signal. HPD_Sink input can be as high as 5V and then HPD_Source will output no higher than 3.3V.			
8	SDA_SOURCE	I/O	3.3V DDC Data I/O. Pulled up by external termination to 3.3V. Connected to SDA_SINK through voltage limiting integrated NMOS passgate.			
9	SCL_SOURCE	I/O	3.3V DDC Data I/O. Pulled up by external termination to 3.3V. Connected to SCL_SINK through voltage-limiting integrated NMOS passgate			
13	OUT_D4+	О	HDMI 1.3 compliant TMDS output. OUT_D4+ makes a differential output signal with OUT_D4			
14	OUT_D4-	О	HDMI 1.3 compliant TMDS output. OUT_D4- makes a differentia output signal with OUT_D4+			
16	OUT_D3+	О	HDMI 1.3 compliant TMDS output. OUT_D3+ makes a differential output signal with OUT_D3			
17	OUT_D3-	О	HDMI 1.3 compliant TMDS output. OUT_D3- makes a differentia output signal with OUT_D3+			
19	OUT_D2+	О	HDMI 1.3 compliant TMDS output. OUT_D2+ makes a differential output signal with OUT_D2			
20	OUT_D2-	О	HDMI 1.3 compliant TMDS output. OUT_D2- makes a differential output signal with OUT_D2+			
22	OUT_D1+	О	HDMI 1.3 compliant TMDS output. OUT_D1+ makes a differential output signal with OUT_D1			
23	OUT_D1-	О	HDMI 1.3 compliant TMDS output. OUT_D1- makes a differential output signal with OUT_D1+			
			Enable for IN_Dx to OUT_Dx level shifter path.			
25	OF#	T	OE# IN_D Termination OUT_D Outputs			
25	OE#	I	1 > 100KΩ High-Z			
			0 50Ω Active			
28	SCL_SINK	I/O	5V DDC Clock I/O. Pulled up by external termination to 5V. Connected to SCL_SOURCE through voltage limiting integrated NMOS passgate.			

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Pin	Name	I/O Type	Descriptions		
29	SDA_SINK	I/O	5V DDC Data I/O. Pulled up by external termination to 5V. Connected to SDA_SOURCE through voltage limiting integrated NMOS passgate.		
30	HPD_SINK	I	Low Frequency, 0V to 5V (nominal) input signal. This signal come from the TMDS connector. Voltage High indicates "plugged" state voltage low indicated "unplugged". HPD_SINK is pulled down by an integrated 100K ohm pull-down resistor.		
				ltage to the DDC passgate level shifter gates. (May d as a bias voltage connection to the DDC pass gates	
32	DDC_EN	I	DDC_EN	Passgate	
			0V	Disable	
			3.3V	Enable	
38	IN_D1-	I	Low-swing diff input from DP Tx outputs. IN_D1- makes a differential pair with IN_D1+.		
39	IN_D1+	I	Low-swing diff input from DP Tx outputs. IN_D1+ makes a differential pair with IN_D1		
41	IN_D2-	I	Low-swing diff input from DP Tx outputs. IN_D2- makes a differ ential pair with IN_D2+.		
42	IN_D2+	I	Low-swing diff input from DP Tx outputs. IN_D2+ makes a differential pair with IN_D2		
44	IN_D3-	I	Low-swing diff input from DP Tx outputs. IN_D3- makes a differential pair with IN_D3+.		
45	IN_D3+	I	Low-swing diff input from DP Tx outputs. IN_D3+ makes a differential pair with IN_D3		
47	IN_D4-	I	Low-swing diff input from DP Tx outputs. IN_D4- makes a differential pair with IN_D4+.		
48	IN_D4+	I	Low-swing diff ferential pair w	input from DP Tx outputs. IN_D4+ makes a difith IN_D4	



Absolute Maximum Ratings (Over operating free-air temperature range)

Item	Rating
Supply Voltage to Ground Potential	5.5V
All Inputs and Outputs	-0.5V to V _{DD} +0.5V
Ambient Operating Temperature	-40 to +85°C
Storage Temperature	-65 to +150°C
Junction Temperature	150°C
Soldering Temperature	260°C

 $Stress\ beyond\ those\ listed\ under\ "Absolute\ Maximum\ Ratings"\ may\ cause\ permanent\ damage\ to\ the\ device.$

Parameter	Min.	Тур.	Max.	Unit
Ambient Operating Temperature	-40		+85	°C
Power Supply Voltage (measured in respect to GND)	+3.0		+3.6	V



Table: Power Supplies and Temperature Range

Symbol	Parameter	Min	Тур	Max	Units	Comments
V_{DD}	3.3V Power supply	3.0	3.3	3.6	V	
I _{CC}	Max Current			100	mA	
I _{CCQ}	Standby Current			2	mA	OE# = HIGH
T _{CASE}	Case temperature range for operation with spec.	-40		85	Celsius (°)	

Table: Differential Input Characteristics for IN_Dx signals

Symbol	Parameter	Min	Тур	Max	Units	Comments
T _{bit}	Unit Interval	360			ps	T_{bit} is determined by the display mode. Nominal bit rate ranges from 250Mbps to 2.5Gbps per lane. Nominal Tbit at 2.5 Gbps = 400 ps. 360ps = 400ps-10%
V _{RX_DIFF}	Input Differential Voltage level	0.175		1.200	V	See note 1 below
T _{RX_EYE}	Minimum Eye Width at IN_D input pair	0.8			T _{bit}	The level shifter may add a maximum of $0.02UI$ jitter $(400 * 0.02) = 8ps$
V _{CM-ACp-p}	AC Peak Common Mode Input Voltage			100	mV	See note 2 below
Z _{RX_DC}		40	50	60	Ω	Required IN_D+ as well as IN_D- DC impedance (50 ±20% tolerance).
Z _{RX-Bias}		0		2.0	V	Intended to limit power-up stress on chipset's PCIE output buffers.
Z _{RX_HIGH-Z}		100			kΩ	Differential inputs must be in a high impedance state when OE# is HIGH.

^{1.} $V_{RX-DIFF} = 2x|V_{RX-D-}V_{RX-D-}|$ Applies to IN_Dx signals

 $V_{RX-CM-DC} = DC(avg) \text{ of } |V_{RX-D+} + V_{RX-D-}|/2$

VCM-AC-p-p includes all frequencies above 30 kHz.

TMDS Outputs

The level shifter's TMDS outputs are required to meet HDMI 1.3 specifications.

The HDMI 1.3 Specification is assumed to be the correct reference in instances where this document conflicts with the HDMI 1.3 specification.

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^{2.} $V_{CM-AC-p-p} = |V_{RX-D} - V_{RX-D}|/2 - V_{RX-CM-DC}$



Truth Table (Slew Rate control function)

SR1	SRO	Rise/Fall Time (Typ)
1	1	140ps
1	0	130ps
0	1	120ps
0	0	110ps

Test Setup Condition

 $V_{\rm DD}$ = 3.3V, Ambient temperture 25°C

Rise/Fall time is from 20% to 80% on Rising/Falling edge

Date rate: 620 Mbps

Input: 1V differential peak-to-peak clock pattern

Equalization: 3dB

Table 1: OE Pin Description

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OE#	Device State	Comments				
Asserted (low voltage)	Differential input buffers and output buffers enabled. Input impedance = 50Ω	Normal functioning state for IN_D to OUT_D level shifting function.				
Unasserted (high voltage)	Low-power state. Differential input buffers and termination are disabled. Differential inputs are in a high impedance state. OUT_D level-shifting outputs are disabled. OUT_D level-shifting outputs are in high impedance state. Internal bias currents are turned off.	Intended for lowest power condition when: No display is plugged in or The level shifted data path is disabled HPD_SINK input and HPD_SOURCE output are not affected by OE# SCL_ SOURCE, SCL_SINK, SDA_SOURCE and SDA_SINK signals and functions are not affected by OE#				

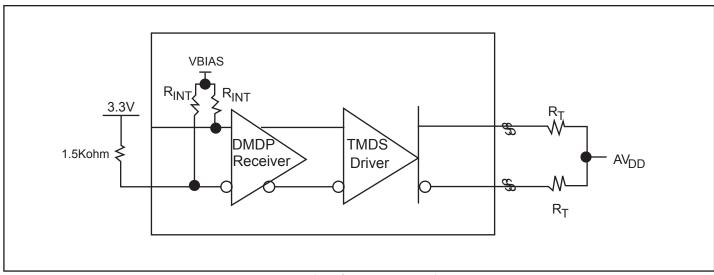
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Symbol	Parameter	Min	Тур	Max	Units	Comments
V _H	Single-ended high level output voltage	V _{DD} -10mV	V_{DD}	V _{DD} +10mV	V	V_{DD} is the DC termination voltage in the HDMI or DVI Sink. V_{DD} is nominally 3.3V
V_{L}	Single-ended low level output voltage	V _{DD} -600mV	V _{DD} -500mV	V _{DD} -400mV	V	The open-drain output pulls down from $V_{\rm DD}$.
Vswing	Single ended output swing voltage	425	500	600	mV	Swing down from TMDS termination voltage (3.3V $\pm 10\%$)
I_{OFF}	Single-ended current in high-Z state			50	μΑ	Measured with TMDS outputs pulled up to V_{DD} Max _(3.6V) through 50 Ω resistors.
Tskew-intra	Intra-pair differential skew			30	ps	This differential skew budget is in addition to the skew presented between D+ and D- paired input pins. HDMI revision 1.3 source allowable intrapair skew is 0.15 T _{bit} .
T _{SKEW-INTER}	Inter-pair lane-to-lane output skew			100	ps	This lane-to-lane skew budget is in addition to skew between differential input pairs
$T_{ m JIT}$	Jitter added to TMDS signals			25	ps	Jitter budget for TMDS signals as they pass through the level shifter. $25ps = 0.056 T_{bit}$ at $2.25 Gb/s$

TMDS output oscillation elimination

The inputs do not incorporate a squelch circuit. Therefore, we recommend the input to be externally biased to prevent output oscillation. Pericom recommends to add a 1.5Kohm pull-up to the CLK- input.



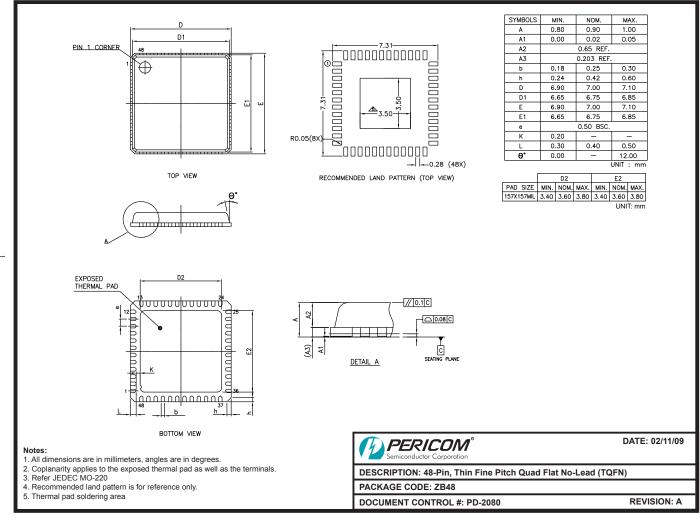
TMDS Input Fail-Safe Recommendation

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Symbol	Parameter	Min	Тур	Max	Units	Comments
V _{IH-HPD}	Input High Level	2.0	5.0	5.3	V	Low-speed input changes state on cable plug/unplug
$V_{\text{IL-HPD}}$	HPD_sink Input Low Level	0		0.8	V	
I _{IN-HPD}	HPD_sink Input Leakage Current			70	μΑ	Measured with HPD_sink at $V_{\text{IH-HPD}}$ max and $V_{\text{IL-HPD}}$ min
V _{OH-HPD}	HPD_source Output High-Level	2.5		V_{DD}	V	$V_{DD} = 3.3V \pm 10\%$ $I_{OH} = -4mA(MIN) / -8mA(MAX)$
V _{OL-HPD}	HPD_source Output Low- Level	0		0.4	V	$I_{OL} = 4mA(MIN) / 8mA(MAX)$
T_{HPD}	HPD_sink to HPD_source propagation delay			200	ns	Time from HPD_sink changing state to HPD_source changing state. Includes HPD_source rise/fall time
$T_{RF ext{-}HPDB}$	HPD_source rise/ fall time	1		20	ns	Time required to transition from $V_{OH-HPDB}$ to $V_{OL-HPDB}$ or from $V_{OL-HPDB}$ to $V_{OH-HPDB}$
Table 4: O	E# Input, DDC_EN		·			
Symbol	Parameter	Min	Тур	Max	Units	Comments
V _{IH}	Input High Level	2.0		V _{DD}	V	TMDS enable input changes state on cable plug/unplug
V _{IL}	Input Low Level	0		0.8	V	
$I_{\rm IN}$	Input Leakage Current			10	μΑ	Measured with input at $V_{\text{IH-EN}}$ max and $V_{\text{IL-EN}}$ min
Table 5: Te	ermination Resistor					
Symbol	Parameter	Min	Тур	Max	Units	Comments
R _{HPD}	HPD_sink input pulldown resistor.	100K			Ω	Guarantees HPD_sink is LOW when no display is plugged in.





09-0091

Note:

• For latest package info, please check: http://www.pericom.com/products/packaging/mechanicals.php

Ordering Information

Ordering Code	Package Code	Package Type
PI3VDP411LSRZBE	ZB	Pb-free & Green, 48-pin TQFN

- 1. Thermal characteristics can be found on the company web site at www.pericom.com/packaging/
- 2. E = Pb-free and Green
- 3. Adding an X suffix = Tape/Reel

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